

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6103	438/4.ccls. 438/15.ccls. 438/17.ccls. 438/18.ccls. 438/107.ccls. 438/113.ccls. 438/122.ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 438/460.ccls.	US-PGPUB; USPAT	OR	OFF	2004/11/10 10:36
L4	1854	((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) same (die dice chip (wafer with (dic\$6 cut\$6 saw\$6)))	US-PGPUB; USPAT	OR	ON	2004/11/10 11:13
L5	0	((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) same ((wafer substrate) with (dic\$6 cut\$6 saw\$6)) same ((memory ram dram sram ??ram) near2 (chip die dice))	US-PGPUB; USPAT	OR	ON	2004/11/10 11:16
L6	0	((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) same ((wafer substrate) with (dic\$6 cut\$6 saw\$6)) same ((memory ram dram sram ??ram) with (chip die dice))	US-PGPUB; USPAT	OR	ON	2004/11/10 11:18
L9	166	((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) same (repair\$6 restor\$8 replac\$6 kgd (known adj good adj die))	US-PGPUB; USPAT	OR	ON	2004/11/10 11:26
L10	30	9 same (test\$6 measur\$6 evaluat\$6)	US-PGPUB; USPAT	OR	ON	2004/11/10 11:24
L13	1631	1 and (repair\$6 restor\$8 replac\$6 kgd (known adj good adj die))	US-PGPUB; USPAT	OR	ON	2004/11/10 11:27
L16	142	(438/4.ccls. 438/15.ccls. 438/17.ccls. 438/18.ccls.) and (438/107.ccls. 438/113.ccls. 438/122.ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 438/460.ccls.)	US-PGPUB; USPAT	OR	OFF	2004/11/10 11:34
L22	65	1 and (repair\$6 restor\$8 replac\$6) and (kgd (known adj good adj die))	US-PGPUB; USPAT	OR	ON	2004/11/10 12:36
L23	234	1 and ((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate)))	US-PGPUB; USPAT	OR	ON	2004/11/10 13:15

L25	160	((gold with (electrode contact finger lead)) same (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) same (((wafer substrate) with (dic\$6 cut\$6 saw\$6)) ((memory ram dram sram ??ram) with (chip die dice)))	US-PGPUB; USPAT	OR	ON	2004/11/10 14:55
L26	116	9 and (test\$6 measur\$6 evaluat\$6)	US-PGPUB; USPAT	OR	ON	2004/11/10 17:09
L27	32	((gold with (electrode contact finger lead)) and (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) and (((wafer substrate) with (dic\$6 cut\$6 saw\$6)) ((memory ram dram sram ??ram) with (chip die dice)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:25
L28	58	((gold with (electrode contact finger lead)) and (mcm module carrier multichip pcb pwb board ((wiring package) adj substrate))) and (repair\$6 restor\$8 replac\$6 kgd (known adj good adj die))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:26